



The GreenMOS[®] high voltage MOSFET utilizes charge balance technology to achieve outstanding low on-resistance and lower gate charge. It is engineered to minimize conduction loss, provide superior switching performance and robust avalanche capability.

The GreenMOS[®] Generic series is optimized for extreme switching performance to minimize switching loss. It is tailored for high power density applications to meet the highest efficiency standards.

- Low $R_{DS(ON)}$ & FOM
- Extremely low switching loss
- Excellent stability and uniformity

- PC power
- LED lighting
- Telecom power
- Server power
- EV Charger
- Solar/UPS



Parameter	Value	Unit
$V_{DS, min} @ T_{j, max}$	850	V

$I_{D, pulse}$

Absolute Maximum Ratings at $T_j=25^{\circ}\text{C}$ unless otherwise noted

Parameter	Symbol	Value	Unit
Drain-source voltage	V_{DS}	800	V
Gate-source voltage	V_{GS}	± 30	V
Continuous drain current ¹⁾ , $T_C=25^{\circ}\text{C}$	I_D	4	A
Continuous drain current ¹⁾ , $T_C=100^{\circ}\text{C}$		2.5	
Pulsed drain current ²⁾ , $T_C=25^{\circ}\text{C}$	$I_{D, pulse}$	12	A
Continuous diode forward current ¹⁾ , $T_C=25^{\circ}\text{C}$	I_S	4	A
Diode pulsed current ²⁾ , $T_C=25^{\circ}\text{C}$	$I_{S, pulse}$	12	A
Power dissipation ³⁾ , $T_C=25^{\circ}\text{C}$	P_D	37	W
Single pulsed avalanche energy ⁵⁾	E_{AS}	100	mJ
MOSFET dv/dt ruggedness, $V_{DS}=0\dots 640\text{ V}$	dv/dt	50	V/ns
Reverse diode dv/dt, $V_{DS}=0\dots 640\text{ V}$, $I_{SD} = I_D$	dv/dt	15	V/ns
Operation and storage temperature	T_{stg}, T_j	-55 to 150	$^{\circ}\text{C}$

Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal resistance, junction-case	R_{JC}	3.4	$^{\circ}\text{C}/\text{W}$
Thermal resistance, junction-ambient ⁴⁾	R_{JA}	62	$^{\circ}\text{C}/\text{W}$

Electrical Characteristics at $T_j=25^{\circ}\text{C}$ unless otherwise specified

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
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D337.75 409.37 61.8

Dynamic Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Input capacitance	C_{iss}		363.5		pF	$V_{GS}=0\text{ V}$, $V_{DS}=50\text{ V}$, $f=1\text{ MHz}$
Output capacitance	C_{oss}		25.5		pF	
Reverse transfer capacitance	C_{rss}		1.35		pF	
Turn-on delay time	$t_{d(on)}$		16.8		ns	$V_{GS}=10\text{ V}$, $V_{DS}=400\text{ V}$, $R_G=25\ \Omega$, $I_D=2\text{ A}$
Rise time	t_r		5.7		ns	
Turn-off delay time	$t_{d(off)}$		31		ns	
Fall time	t_f		42.8		ns	

Gate Charge Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Total gate charge	Q					

Electrical Characteristics Diagrams

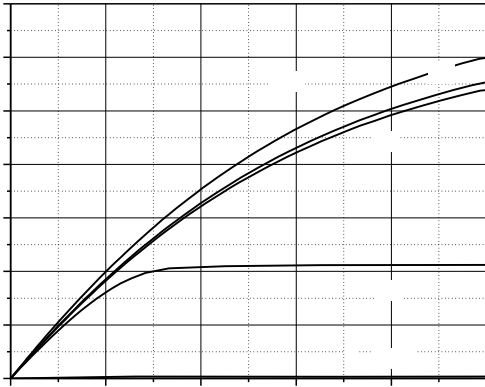


Figure 1. Typ. output characteristics



Figure 2. Typ. transfer characteristics

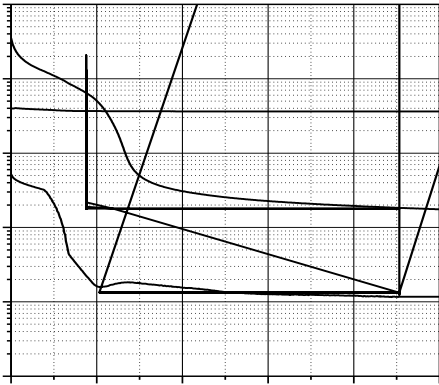


Figure 3. Typ. capacitances

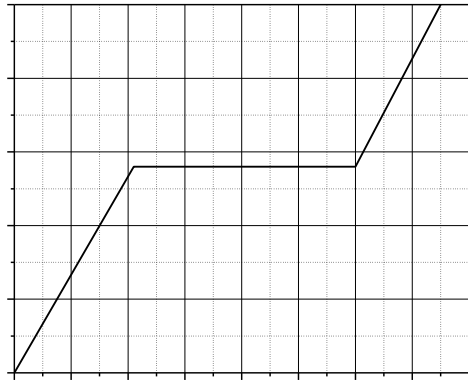


Figure 4. Typ. gate charge



Figure 5. Drain-source breakdown voltage

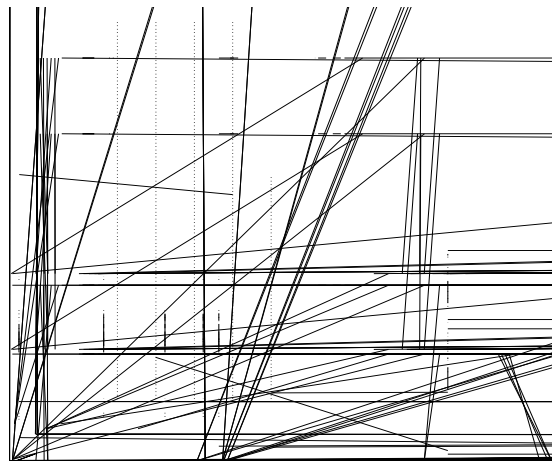


Figure 6. Drain-source on-state resistance

Test circuits and waveforms

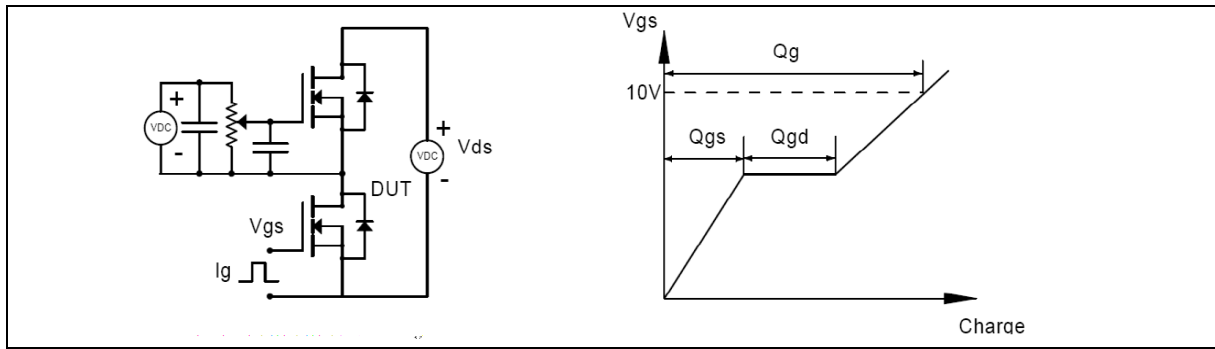


Figure 1. Gate charge test circuit & waveform

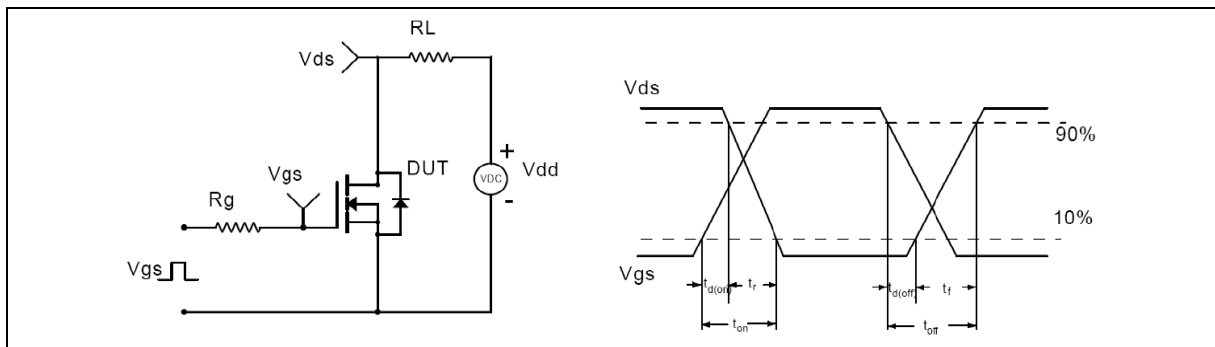


Figure 2. Switching time test circuit & waveforms

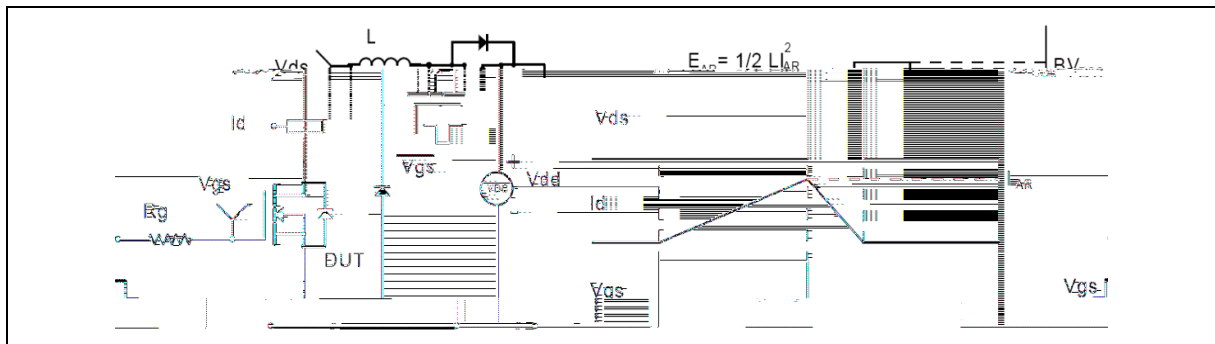


Figure 3. Unclamped inductive switching (UIS) test circuit & waveforms

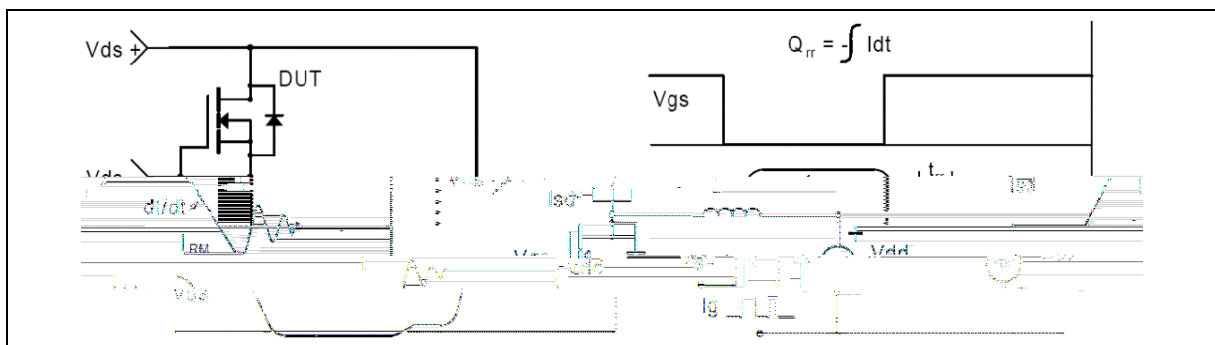
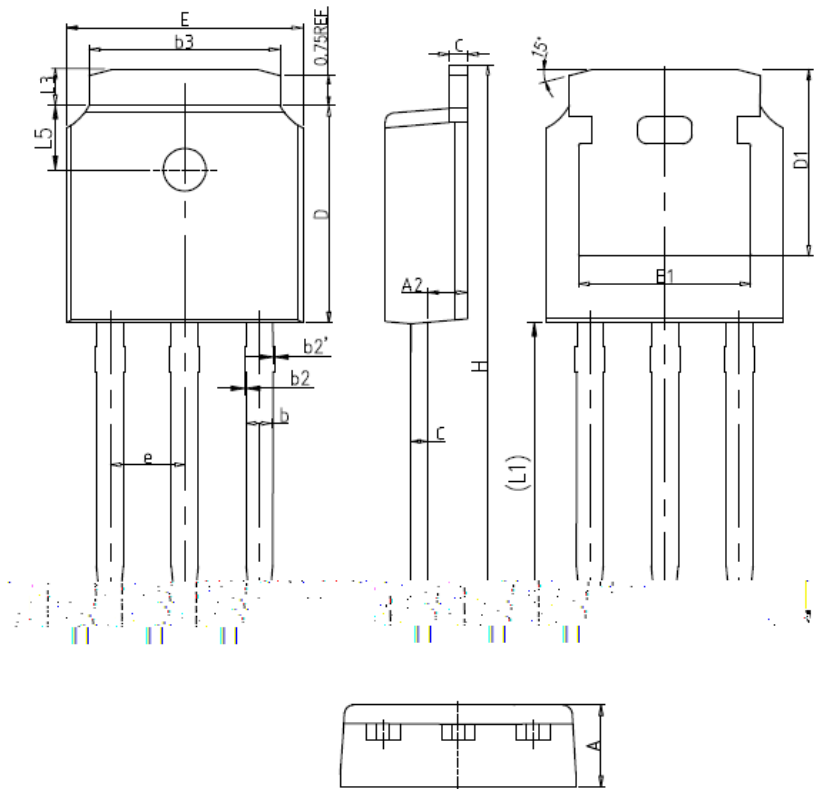


Figure 4. Diode reverse recovery test circuit & waveforms

Package Information



Symbol	mm		
	Min	Nom	Max
A	2.20	2.30	2.40
A2	0.97	1.07	1.17
b	0.68	0.78	0.90
b2	0.00	0.04	0.10
b2'	0.00	0.04	0.10
b3	5.20	5.33	5.50
c	0.43	0.53	0.63
D	5.98	6.10	6.22
D1	5.30REF		
E	6.40	6.60	6.80
E1	4.63	-	-
e	2.286BSC		
H	16.22	16.52	16.82
L1	9.15	9.40	9.65
L3	0.88	1.02	1.28
L5	1.65	1.80	1.95

Version 1: TO251-C package outline dimension

Ordering Information

Package Type	Units/ Tube	Tubes/ Inner Box	Units/ Inner Box	Inner Boxes/ Carton Box	Units/ Carton Box
TO251-C	75	66	4950	6	29700

Product Information

Product	Package	Pb Free	RoHS	Halogen Free
OSG80R1K4AF	TO251	yes	yes	yes

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